

Bill Of Materials Page1

Item	Quantity	Reference	Part
1	1	C1	0.015uF
2	3	C2,C3,C4	0.1uF
3	3	JMP1,JMP2,JMP3	Header 2x1
4	1	J1	SAMTEC_FTMH-102-03-L-DH
5	1	R1	3.9k
6	2	R2, R3	0 Ohm
7	1	R4	0 Ohm
8	1	R5	75 ohm
9	1	D1	Green LED 0603
10	1	U1	TUSB211RWB
11	1	U2	LP5907
12	1	PCB	PCB Board

Manufacture	Manufacture Part Number	PCB Footprint
TDK	C1005X5R1E153K050BA	0402
TDK	C1005X5R1A104K050BA	0402
Sullins Connector Solutions	PEC02SAAN	HDR_THVT_1x2_100
Samtec	FTMH-102-03-L-DH	HDR_SMRT_2x2_39_FTMH
Panasonic Electronic Components	ERJ-2GEJ392X	0402
Panasonic Electronic Components	ERJ-1GN0R00C	0201
Panasonic Electronic Components	ERJ-2GE0R00X	0402
Panasonic Electronic Components	ERJ-2RKF75R0X	0402
Lite-On	LTST-C190KGKT	LED_LTST-C190KGKT
Texas Instruments	TUSB211RWBR	RWB
Texas Instruments	LP5907MFX-3.3/NOPB	DBV_R-PDSO-G5
ANY	INT037	

## Description

CAP CER 0.015UF 25V X5R 0402

CAP CER 0.1UF 10V X5R 0402

CONN HEADER .100 SINGL STR 2POS

CONN HEADER 4POS DL 1MM R/A SMD

RES SMD 3.9K OHM 5% 1/10W 0402

RES SMD 0.0OHM JUMPER 1/20W 0201

RES SMD 0.0OHM JUMPER 1/10W 0402

RES SMD 75 OHM 1% 1/10W 0402

LED GREEN CLEAR 0603 SMD

IC USB HUB I/O CONTROL 12X2QFN

IC REG LDO 3.3V 0.25A SOT23-5

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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